
Bluetooth® Class 1 Module from Murata

FEATURES

- **2.4 GHz Bluetooth v2 Class 1**
- **Antenna: On-board Chip Antenna**
- **Dimensions: 17.5 mm x 16 mm x 2 mm**
- **Transmit Output Power: +18 dBm**
- **Receive Sensitivity: –92 dBm**
- **Data Rate Support: BDR**
- **Supply Voltage: 2.2 V to 3.3 V**
- **32 kHz Clock Circuit: On-module**
- **Host Interface: UART**
- **Operating Temperature: –40°C to 85°C**
- **RoHS Compliant**
- **MSL Level 3**
- **FCC, IC certified, CE compliant**

APPLICATIONS

- **Home Automation**
- **Home Energy Management System**
- **Industrial Control and Monitoring**
- **Healthcare and Fitness Device**

DESCRIPTION

SN2100 is a complete industrial grade high power (class 1) *Bluetooth*® module with on-board antenna for M2M application. It integrates *Bluetooth*® IC, PA, RF front end, TCXO and chip antenna into a small LGA form factor and can be simply dropped into the OEM's design. The SN2100 offers total 110 dB link budget, which is significantly better than most of the *Bluetooth*® modules do in the market. This makes it a good fit for industrial control application that usually requires longer distance coverage. The module offers extended product life and industrial standard operating temperature range to fit the industrial usage. The module offers standard HCI interface to the host CPU.

More information on the product can be found on Murata's website:

- Product Overview: <http://www.murata-ws.com/sn2100.htm>
- Data sheet:
http://www.murata-ws.com/view.php?http://www.murata-ws.com/datastore/media/bt_sn2100_ds.pdf

More information on TI's wireless platform solutions for *Bluetooth* can be found on TI's Wireless Connectivity Wiki (www.ti.com/connectivitywiki).



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